

210854US-2S



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
NAGAHISA WATANABE : EXAMINER: PATEL, I. B.
SERIAL NO: 09/899,156 :
FILED: JULY 6, 2001 : GROUP ART UNIT: 2827
FOR: PRINTED WIRING BOARD :
HAVING VIA AND METHOD OF
MANUFACTURING THE SAME

#9/B
Anddt
J. McNeill
12/3/02

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated August 14, 2002, please amend the above-identified application as follows:

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IN THE SPECIFICATION

Please replace the paragraph at page 23, lines 4-13, with the following paragraph:¹

The inner surface of the via 7 is covered with a first plating layer 8. The first plating layer 8 functions as a groundwork for conductivity. The first plating layer 8 continuously covers the rear surface of the wiring layer 4 exposed within the via 7. The first plating layer 8 has a flange portion 9 extending to the first surface 2a of the insulating layer 2 from the one

¹A marked-up copy of the amended portion of the specification is attached hereto.